

# IGBT Modules

## H-Bridge

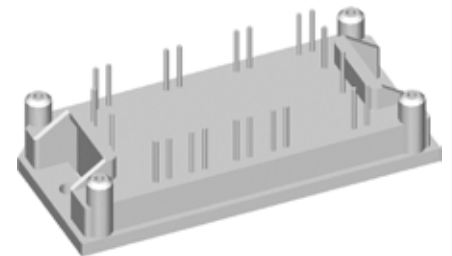
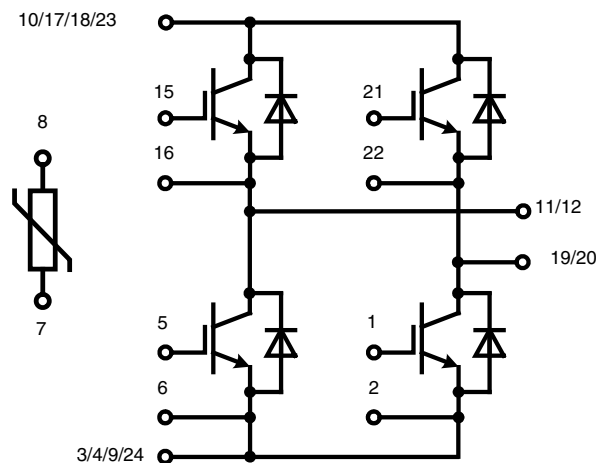
### Trench IGBT

$I_{C25} = 89\text{ A}$   
 $V_{CES} = 600\text{ V}$   
 $V_{CE(sat) \text{ typ.}} = 1.8\text{ V}$

Preliminary data

**Part name** (Marking on product)

MKI 80-06T6K



**Features:**

- Trench IGBT technology
- Low saturation voltage
- Low switching losses
- Square RBSOA, no latch up
- High short circuit capability
- Positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- Ultra fast free wheeling diodes
- Solderable pins for PCB mounting
- Space saving
- Reduced protection circuits

**Application:**

- AC motor control
- AC servo and robot drives
- Power supplies

**Package:**

- Industry standard E1-pack
- Designed for wave soldering
- With copper base plate

IGBTs						
Symbol	Definitions	Conditions	Ratings			Unit
			min.	typ.	max.	
$V_{CES}$	collector emitter voltage	$T_{VJ} = 25^{\circ}\text{C to } 150^{\circ}\text{C}$			600	V
$V_{GES}$	max. DC gate voltage	continuous			$\pm 20$	V
$V_{GEM}$	max. transient collector gate voltage	transient			$\pm 30$	V
$I_{C25}$	collector current	$T_C = 25^{\circ}\text{C}$			89	A
$I_{C80}$		$T_C = 80^{\circ}\text{C}$			67	A
$P_{tot}$	total power dissipation	$T_C = 25^{\circ}\text{C}$			210	W
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 75\text{ A}; V_{GE} = 15\text{ V}$			1.8 2.3	V V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 1.2\text{ mA}; V_{GE} = V_{CE}$	5		6.5	V
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0\text{ V}$			0.5	mA mA
$I_{GES}$	gate emitter leakage current	$V_{CE} = 0\text{ V}; V_{GE} = \pm 20\text{ V}$			400	nA
$C_{ies}$	input capacitance	$V_{CE} = 25\text{ V}; V_{GE} = 0\text{ V}; f = 1\text{ MHz}$			4620	pF
$Q_{G(on)}$	total gate charge	$V_{CE} = 480\text{ V}; V_{GE} = 15\text{ V}; I_C = 75\text{ A}$			470	nC
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 300\text{ V}; I_C = 75\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 5.1\ \Omega$				
$t_r$	current rise time					
$t_{d(off)}$	turn-off delay time					
$t_f$	current fall time					
$E_{on}$	turn-on energy per pulse					
$E_{off}$	turn-off energy per pulse					
$I_{CM}$	reverse bias safe operating area	RBSOA; $V_{GE} = \pm 15\text{ V}; R_G = 5.1\ \Omega; L = 100\ \mu\text{H}$			150	A
$V_{CEK}$		clamped inductive load; $T_{VJ} = 125^{\circ}\text{C}$			0.9x	$V_{CES}$
$t_{SC}$ (SCSOA)	short circuit safe operating area	$V_{CE} = 480\text{ V}; V_{GE} = \pm 15\text{ V}; R_G = 5.1\ \Omega; \text{non-repetitive}$			6	$\mu\text{s}$
$R_{thJC}$	thermal resistance junction to case	(per IGBT)			0.6	K/W
$R_{thCH}$	thermal resistance case to heatsink	(per IGBT)			0.2	K/W

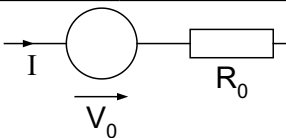
Diodes						
Symbol	Definitions	Conditions	Maximum Ratings			Unit
			min.	typ.	max.	
$V_{RRM}$	max. repetitive reverse voltage				600	V
$I_{F25}$	forward current	$T_C = 25^{\circ}\text{C}$			105	A
$I_{F80}$		$T_C = 80^{\circ}\text{C}$			67	A
Symbol	Conditions	Characteristic Values				Unit
		min.	typ.	max.		
$V_F$	forward voltage	$I_F = 75\text{ A}$	$T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$	1.8 1.6	2.2	V V
$I_{RM}$	max. reverse recovery current	$V_R = 300\text{ V}; I_F = 75\text{ A}$ $di_F/dt = -600\text{ A}/\mu\text{s}$	$T_{VJ} = 100^{\circ}\text{C}$	36		A
$t_{rr}$	reverse recovery time			100		ns
$R_{thJC}$	thermal resistance junction to case	(per diode)	$T_{VJ} = 25^{\circ}\text{C}$		0.65	K/W
$R_{thCH}$	thermal resistance case to heatsink	(per diode)		0.25		K/W

**Temperature Sensor NTC**

Symbol	Definitions	Conditions	Ratings			Unit
			min.	typ.	max.	
$R_{25}$	<i>resistance</i>	$T_C = 25^\circ\text{C}$	4.45	4.7	5.0	$\text{k}\Omega$
$B_{25/85}$				3510		K

**Module**

Symbol	Definitions	Conditions	Ratings			Unit
			min.	typ.	max.	
$T_{VJ}$	<i>operating temperature</i>		-40		125	$^\circ\text{C}$
$T_{VJM}$	<i>max. virtual junction temperature</i>				175	$^\circ\text{C}$
$T_{stg}$	<i>storage temperature</i>		-40		125	$^\circ\text{C}$
$V_{ISOL}$	<i>isolation voltage</i>	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$			2500	V~
$M_d$	<i>mounting torque</i>	(M4)	2.0		2.2	Nm
$d_s$	<i>creep distance on surface</i>		12.7			mm
$d_A$	<i>strike distance through air</i>		12.7			mm
<b>Weight</b>				40		g

**Equivalent Circuits for Simulation**

**Ratings**

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$V_0$	<i>IGBT</i>	$T_{VJ} = 125^\circ\text{C}$		0.9		V
$R_0$				14.3		$\text{m}\Omega$
$V_0$	<i>free wheeling diode</i>	$T_{VJ} = 125^\circ\text{C}$		1.25		V
$R_0$				3		$\text{m}\Omega$



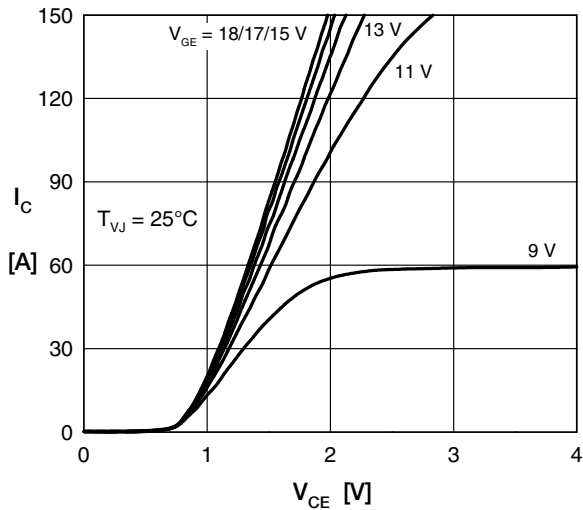


Fig. 1 Typical output characteristics

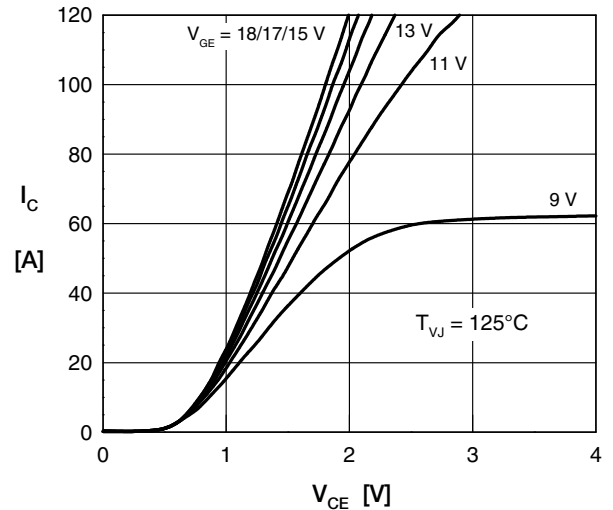


Fig. 2 Typical output characteristics

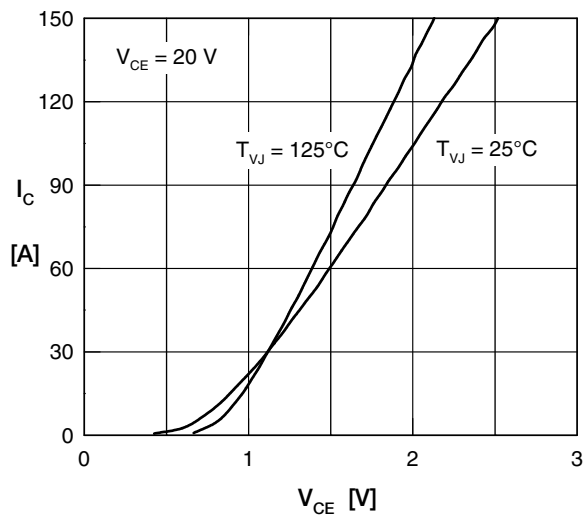


Fig. 3 Typical output characteristics

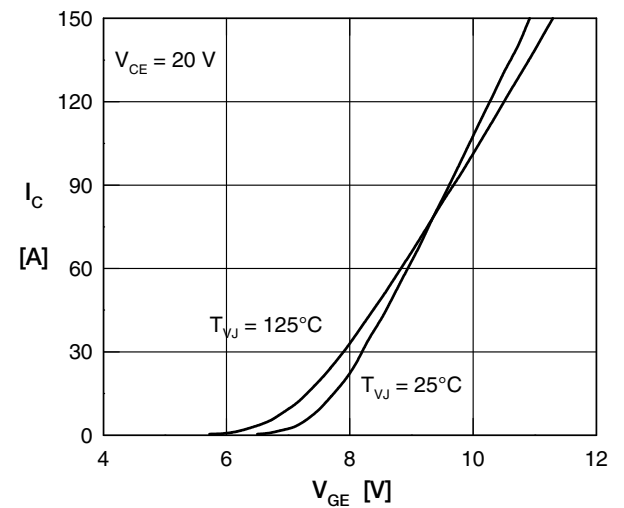


Fig. 4 Typical transfer characteristics

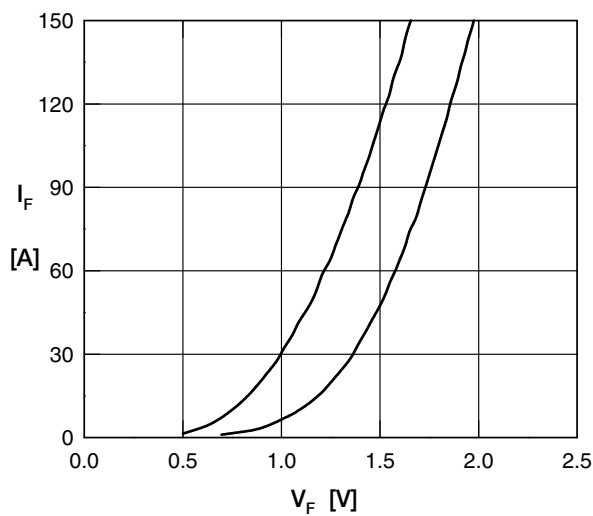


Fig. 5 Typical forward characteristics FWD

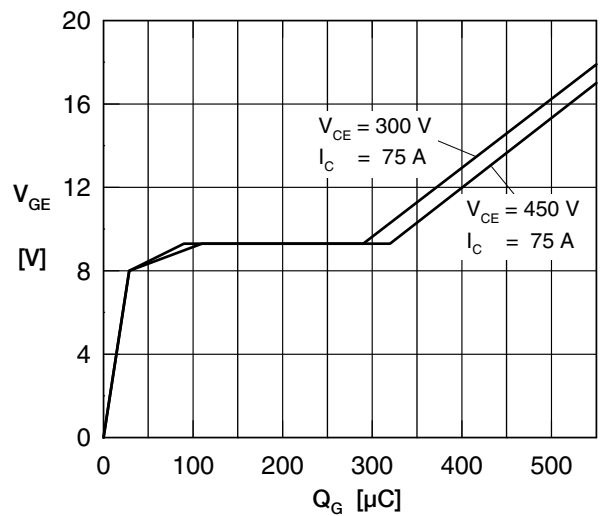


Fig. 6 Typical turn-on gate charge